



Data Taken As IRM With External IF Hybrid

Conversion Gain vs. Temperature

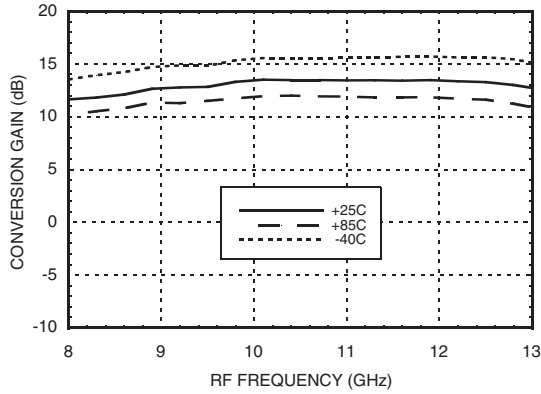
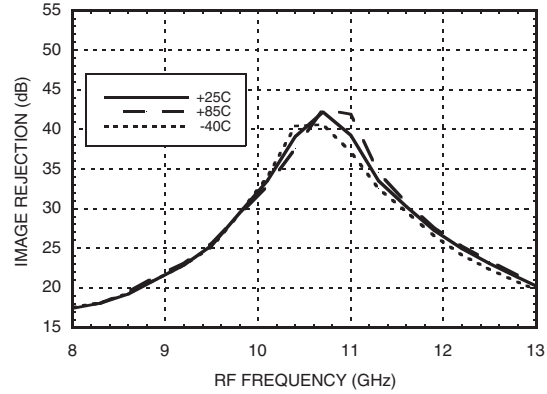
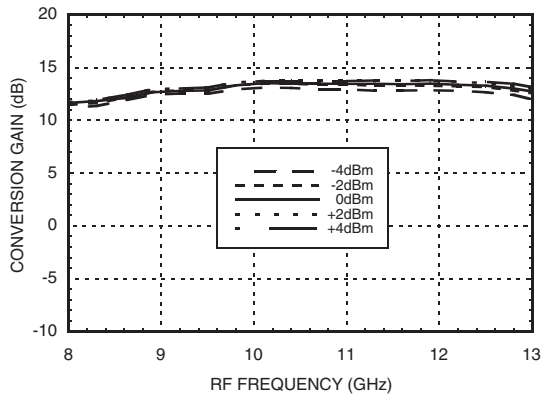


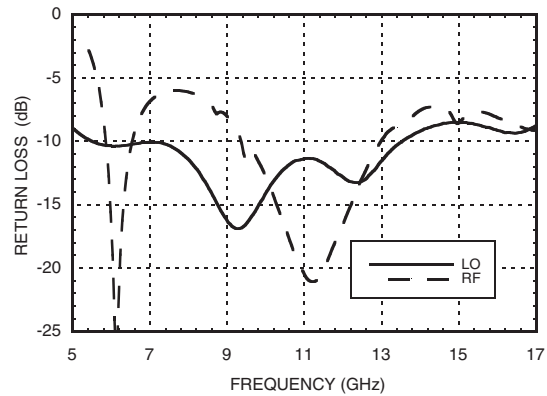
Image Rejection vs. Temperature



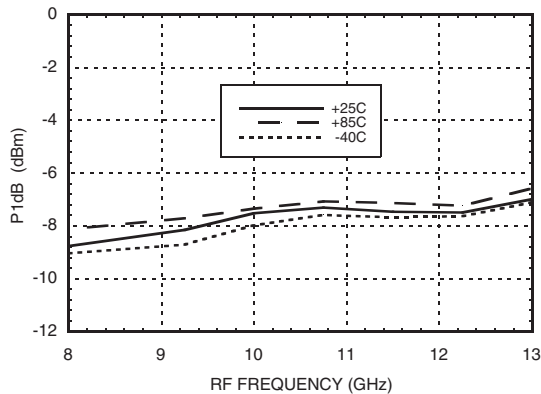
Conversion Gain vs. LO Drive



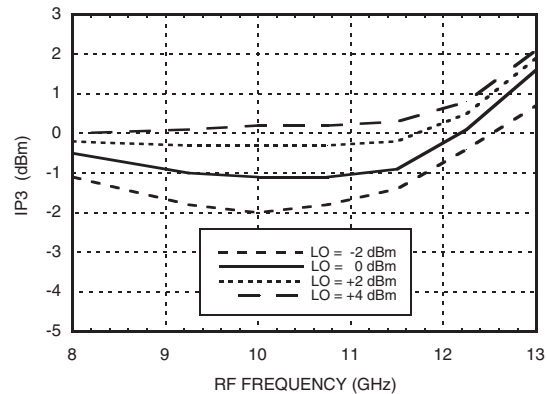
Return Loss



Input P1dB vs. Temperature



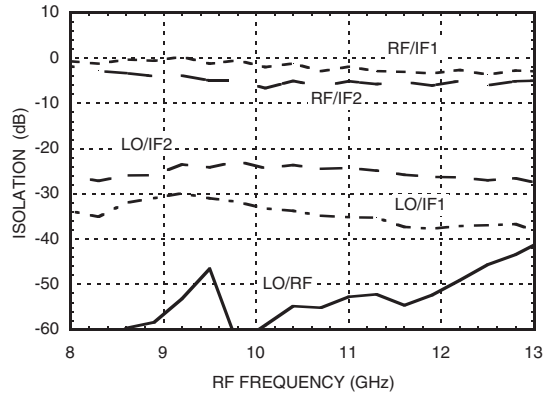
Input IP3 vs. LO Drive



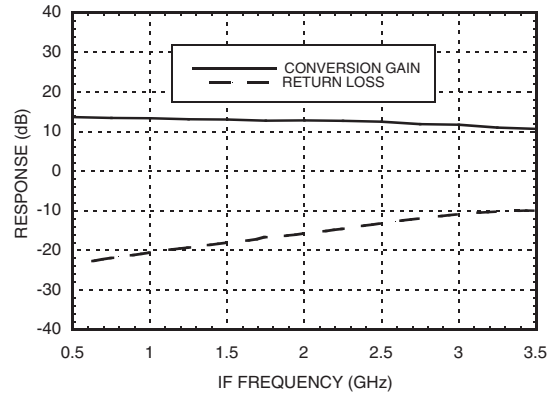


Quadrature Channel Data Taken Without IF Hybrid

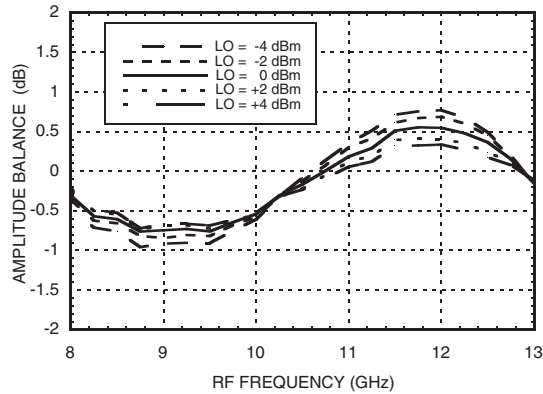
Isolations



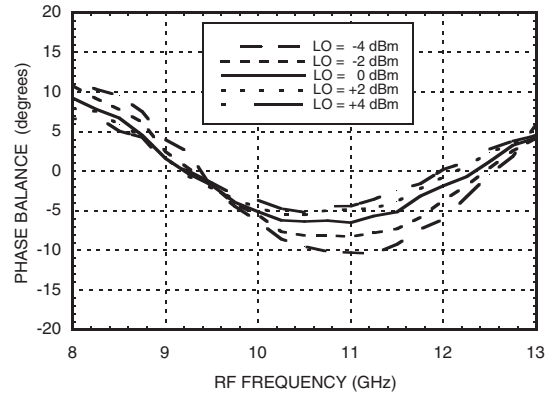
IF Bandwidth*



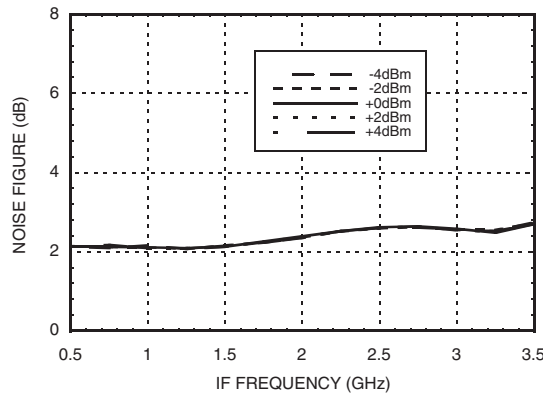
Amplitude Balance vs. LO Drive



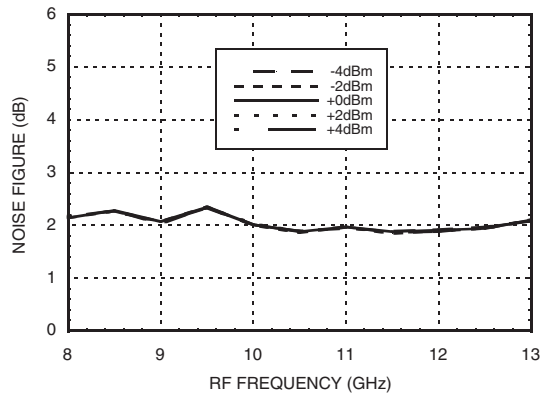
Phase Balance vs. LO Drive



Noise Figure vs. LO Drive, LO Frequency = 10 GHz



Noise Figure vs. LO Drive, IF Frequency = 100 MHz



* Conversion gain data taken with external IF hybrid, LO frequency fixed at 10 GHz and RF varied



MxN Spurious Outputs

mRF	nLO				
	0	1	2	3	4
0	xx	11	21	32	42
1	11	0	10	21	31
2	21	11	0	10	21
3	32	21	11	0	10
4	42	32	21	11	0

RF = 10.6 GHz @ -20 dBm
LO = 10.5 GHz @ 0 dBm
Data taken without IF hybrid
All values in dBc below IF power level.

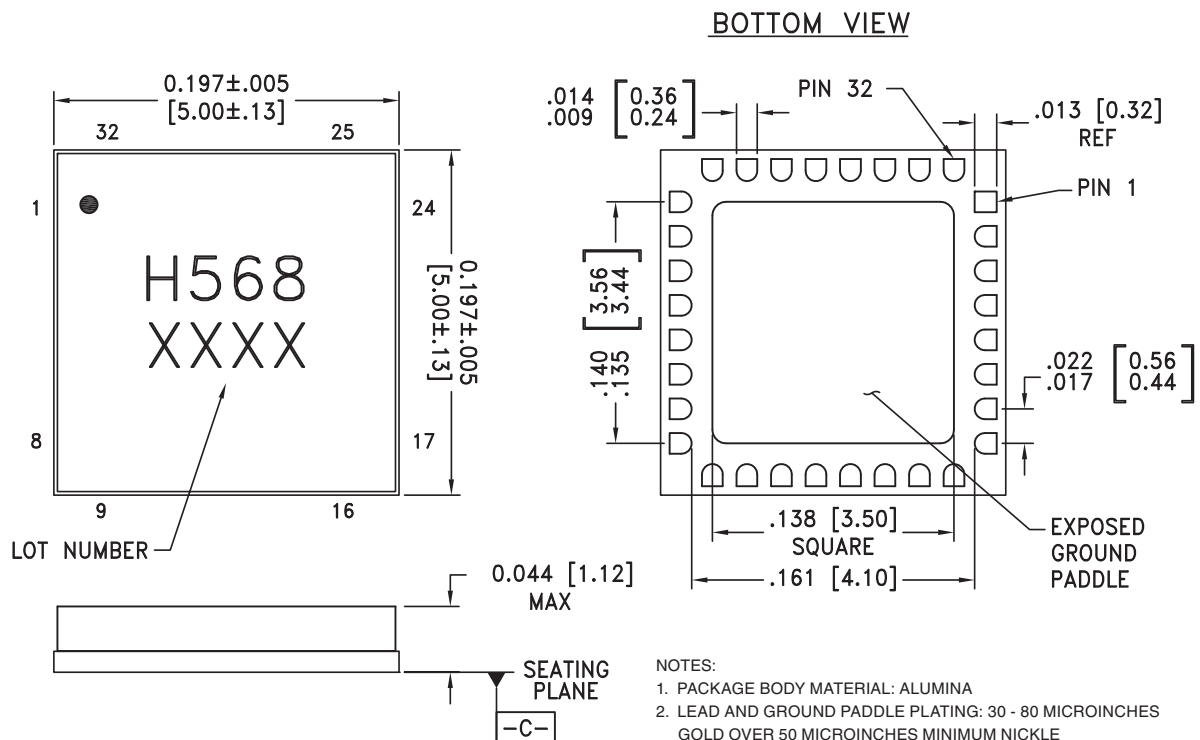
Absolute Maximum Ratings

RF	+5 dBm
LO Drive	+20 dBm
VD1, VD2	4.0V
VD3	5.5V
Channel Temperature	150°C
Continuous Pdiss (T=85°C) (derate 9.56 mW/°C above 85°C)	0.65 W
Thermal Resistance (R _{TH}) (channel to package bottom)	71 °C/W
Storage Temperature	-65 to +150 °C
Operating Temperature	-55 to +85 °C



ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS

Outline Drawing



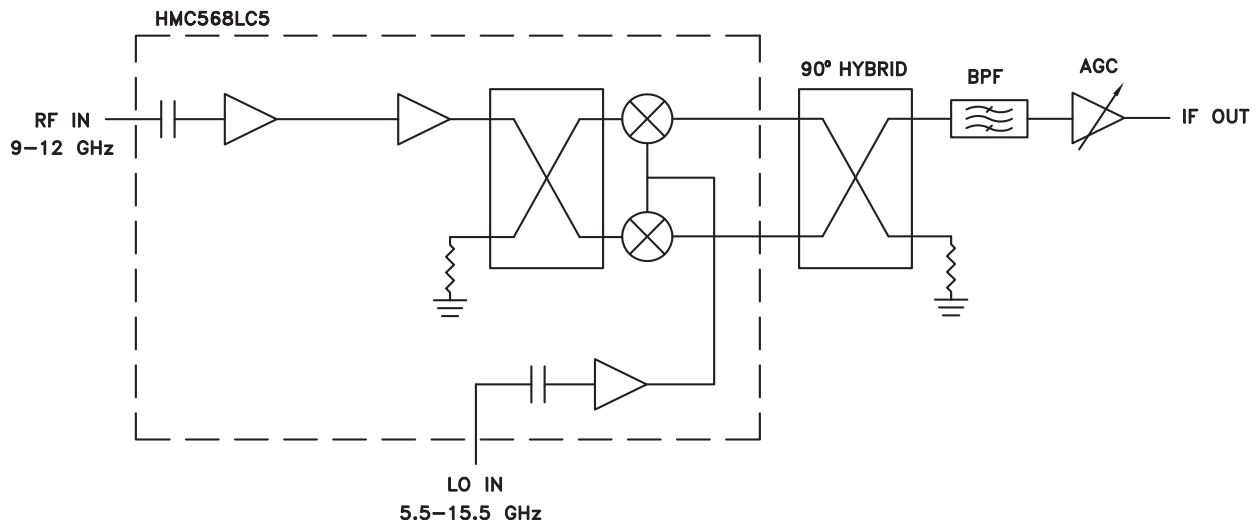
- NOTES:
- PACKAGE BODY MATERIAL: ALUMINA
 - LEAD AND GROUND PADDLE PLATING: 30 - 80 MICROINCHES GOLD OVER 50 MICROINCHES MINIMUM NICKLE
 - DIMENSIONS ARE IN INCHES [MILLIMETERS]
 - LEAD SPACING TOLERANCE IS NON-CUMULATIVE
 - PACKAGE WARP SHALL NOT EXCEED 0.05mm DATUM
 - ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND



Pin Descriptions

Pin Number	Function	Description	Interface Schematic
1, 5, 7 - 9, 13 - 16, 22 - 27, 30 - 32	N/C	No connection required. These pins may be connected to RF/DC ground without affecting performance.	
2, 4, 10, 12, 17, 19, 21	GND	These pins and ground paddle must be connected to RF/DC ground.	
3	RF	This pin is AC coupled and matched to 50 Ohms.	
6	VD3	Power supply for LO amplifier. 100 mA typical, 120 mA maximum.	
28, 29	VD1, VD2	Power supply for RF LNA. 60 mA typical, 88 mA maximum.	
18	IF2	This pin is DC coupled for applications not requiring operation to DC. This port should be DC blocked externally using a series capacitor whose value has been chosen to pass the necessary frequency range. For operation to DC, this pin must not sink / source more than 3 mA of current or part non-function and possible failure will result.	
20	IF1		
11	LO	This pin is AC coupled and matched to 50 Ohms.	

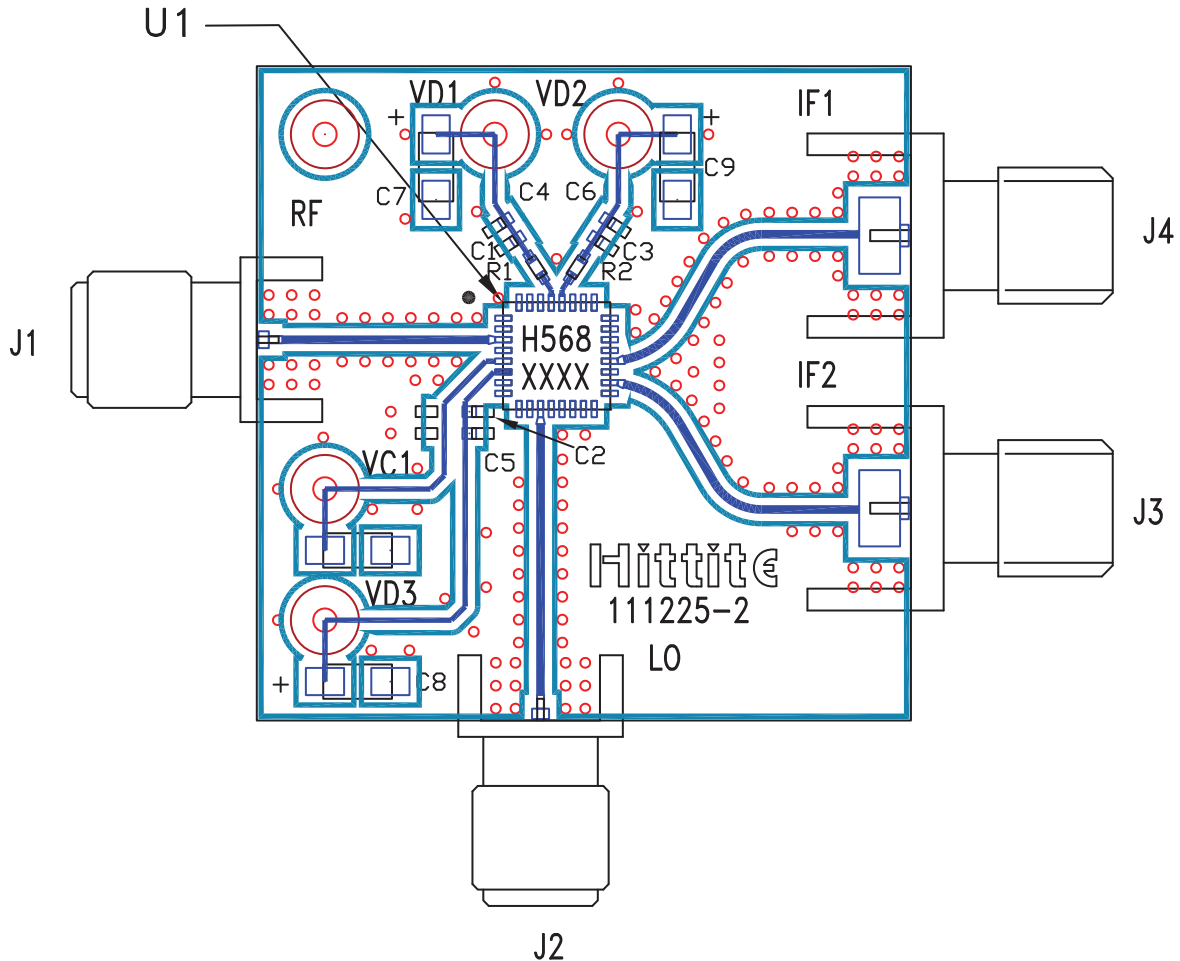
Typical Application



Note: LSB and USB is determined by GND on Hybrid



Evaluation PCB



List of Materials for Evaluation PCB 111227 [1]

Item	Description
C1, C2, C3	Capacitor 0402, Pkg. 100pF
C4, C5, C6	Capacitor 0402, Pkg. 1000pF
C7, C8, C9	Capacitor, Case A, 2.2uF *(Polarity)
J1, J2	PCB Mount SMA RF Connector, SRI
J3, J4	PCB Mount SMA Connector, Johnson
J5, C6	DC Pin
J7	DC Pin
R1, R2	Resistor, 0402 Pkg. 0 Ohm
U1	HMC568LC5
VC1	N/C
PCB [2]	111225 Evaluation Board

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the final application should use RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.